

**FH18P04G****P-Channel Enhancement Mode MOSFET****General Description**

The FH18P04G uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a widevariety of applications.

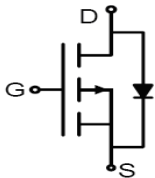
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100% ΔVds TESTED!

Features

- VDS = -40V, ID = -80A
RDS(ON) (Typ) :4.3 mΩ @ VGS = -10V
RDS(ON) (Typ) :5.9 mΩ @ VGS = -4.5V
- High Power and current handing capability
- Lead free product is acquired

Applications

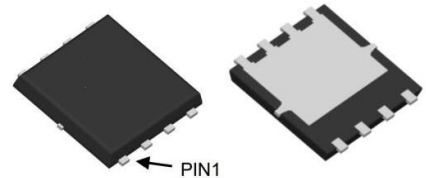
- Load switch
- Power Management
- PWM Applications



Schematic Diagram



Marking and pin Assignment



PDFN5X6-8L top&bottom view

Table 1. Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	-40	V
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V
I _D	Drain Current-Continuous(T _C =25°C)	-80	A
	Drain Current-Continuous(T _C =100°C)	-51	A
I _{DM (pluse)}	Drain Current-Continuous@ Current-Pulsed (Note 1)	-320	A
P _D	Maximum Power Dissipation(T _C =25°C)	58	W
	Maximum Power Dissipation(T _C =100°C)	23	W
E _{AS}	Avalanche energy (Note 2)	576	mJ
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case		2.15	°C/W

Table 3. Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

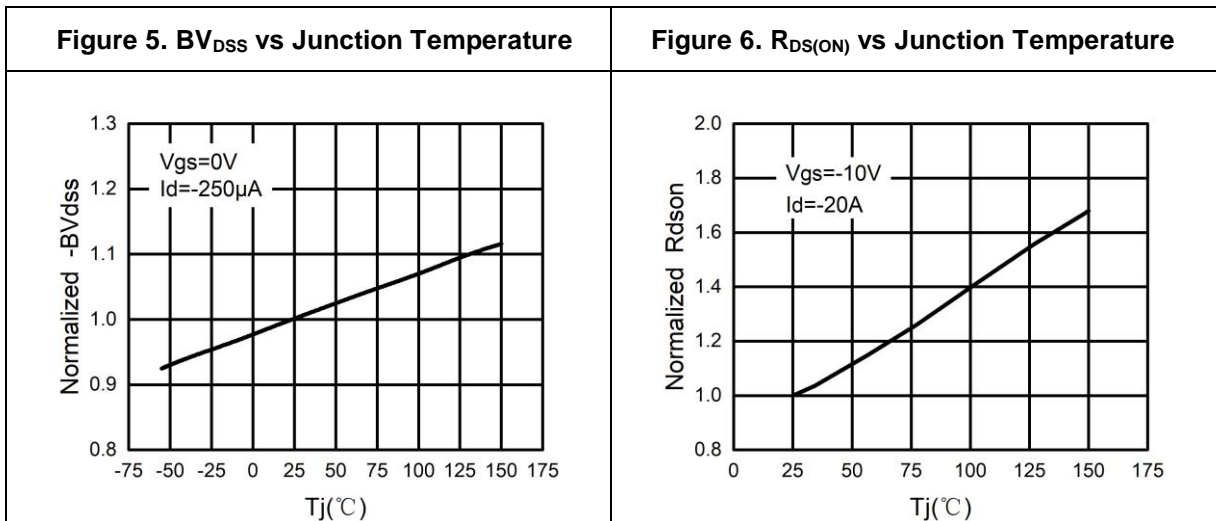
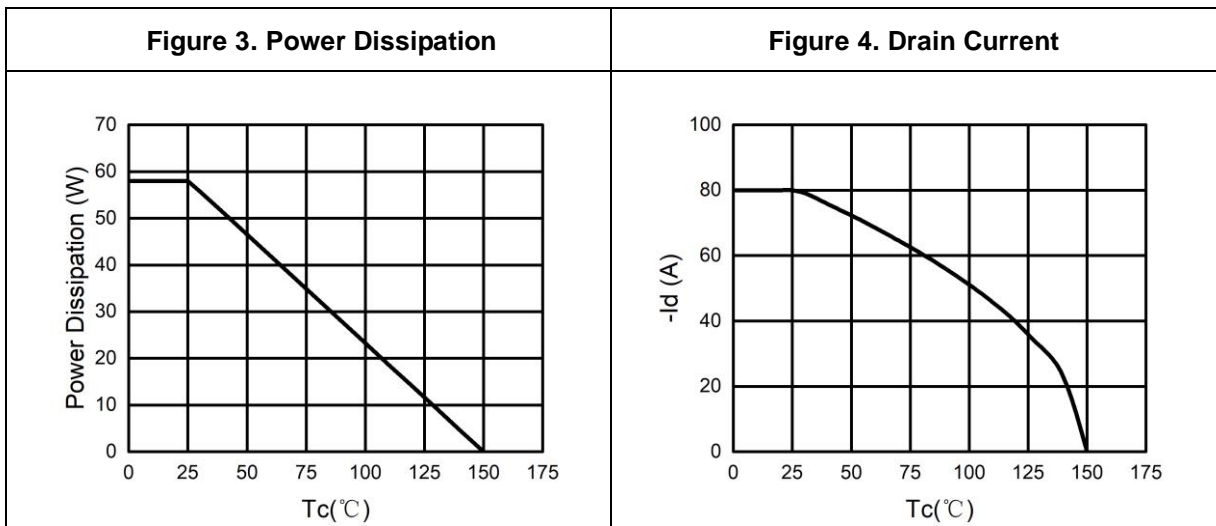
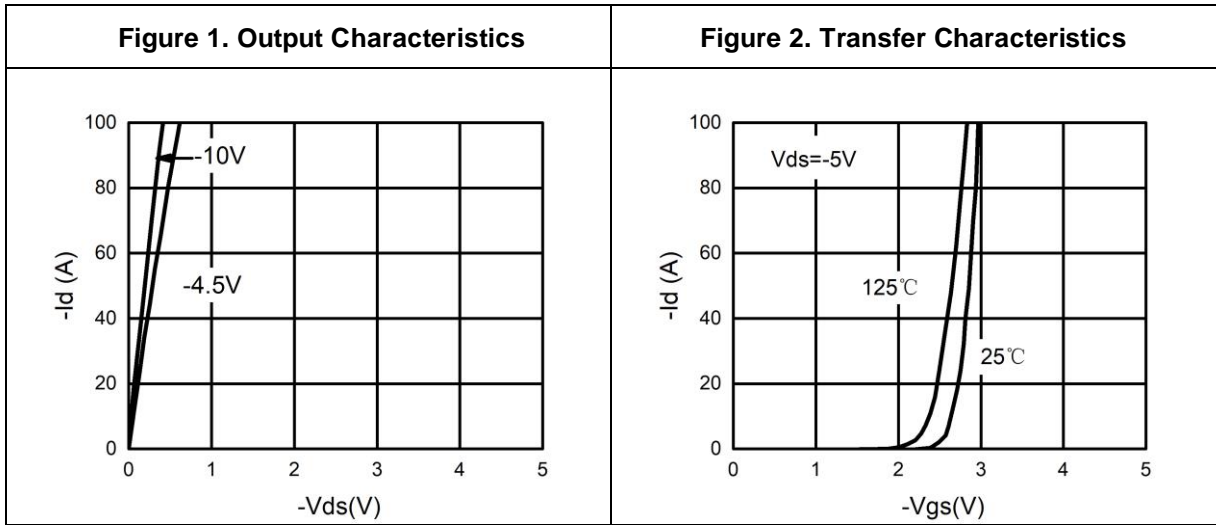
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-40V, V_{GS}=0V$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.7	-2.5	V
g_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-20A$		63		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-20A$		4.3	5.3	m Ω
		$V_{GS}=-4.5V, I_D=-20A$		5.9	7.6	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-20V, V_{GS}=0V, f=1.0MHz$		6638		pF
C_{oss}	Output Capacitance			545		pF
C_{rss}	Reverse Transfer Capacitance			345		pF
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0MHz$		2.2		Ω
Switching Parameters						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=-10V, V_{DS}=-20V, R_L=1\Omega, R_{GEN}=3\Omega$		16		nS
t_r	Turn-on Rise Time			17		nS
$t_{d(off)}$	Turn-Off Delay Time			68		nS
t_f	Turn-Off Fall Time			31		nS
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-20V, I_D=-20A$		118		nC
Q_{gs}	Gate-Source Charge			13		nC
Q_{gd}	Gate-Drain Charge			22		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-80	A
V_{SD}	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=-20A$			-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-20A, di/dt=500A/\mu s$		24		ns
Q_{rr}	Reverse Recovery Charge	$I_F=-20A, di/dt=500A/\mu s$		140		nC

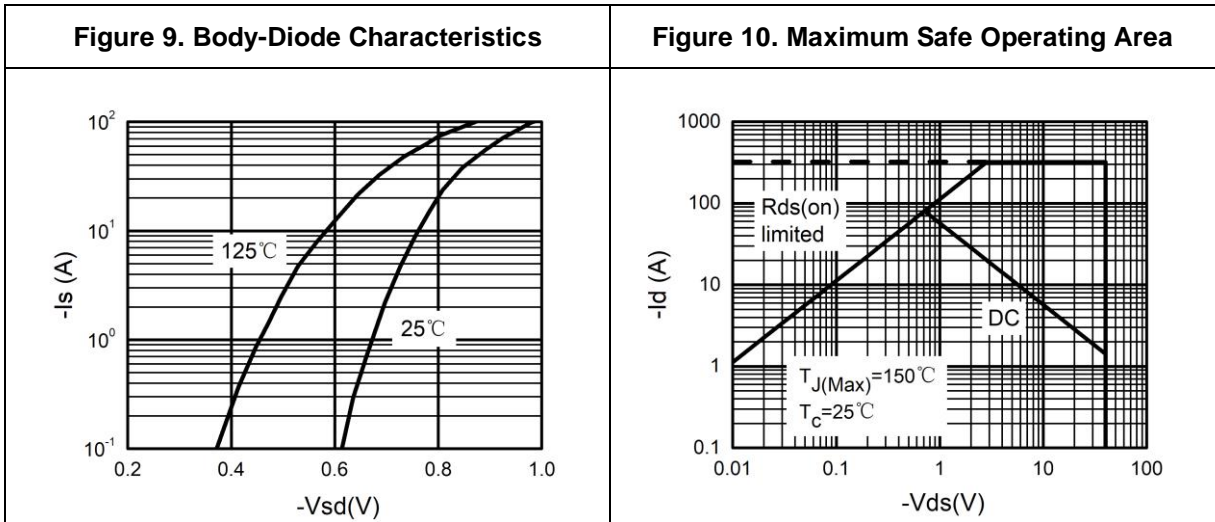
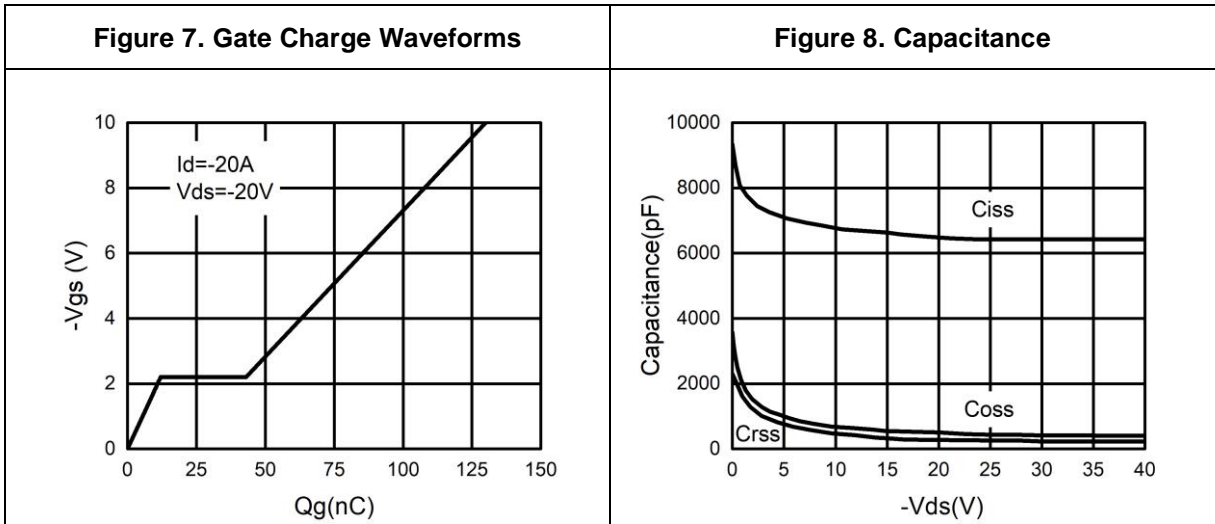
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2. E_{AS} condition: $T_J=25^\circ\text{C}, V_{DD}=15V, V_G=-10V, R_g=25\Omega, L=0.5mH$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

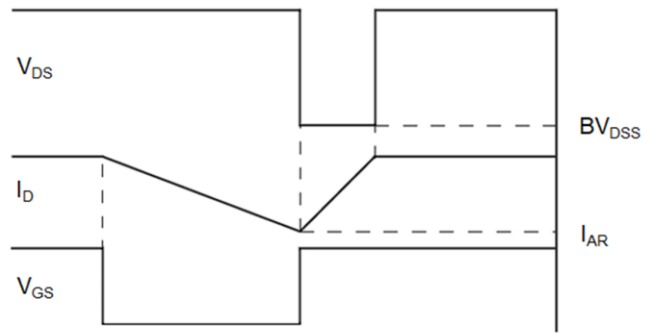
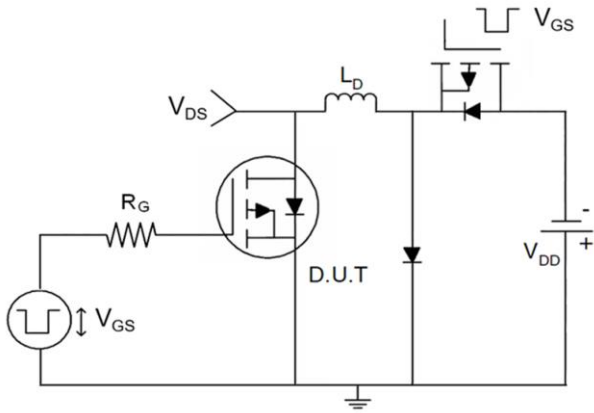
Typical Electrical And Thermal Characteristics (Curves)



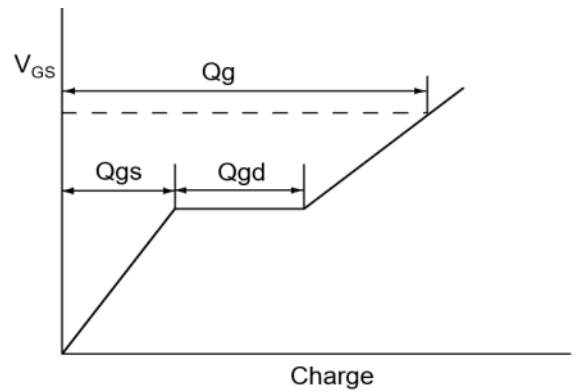
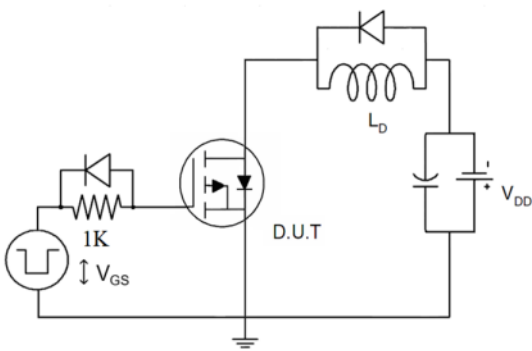


Test Circuit

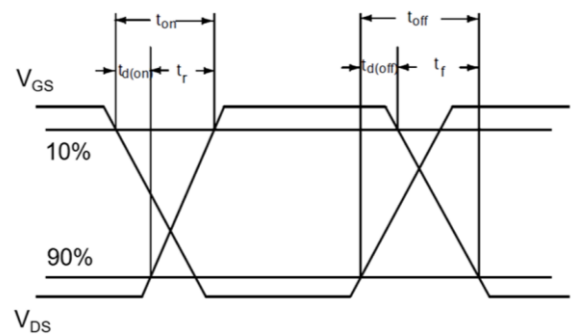
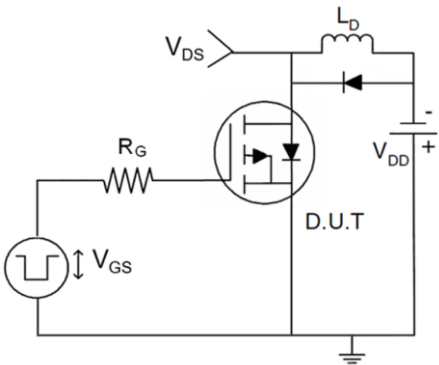
1) E_{AS} Test Circuits



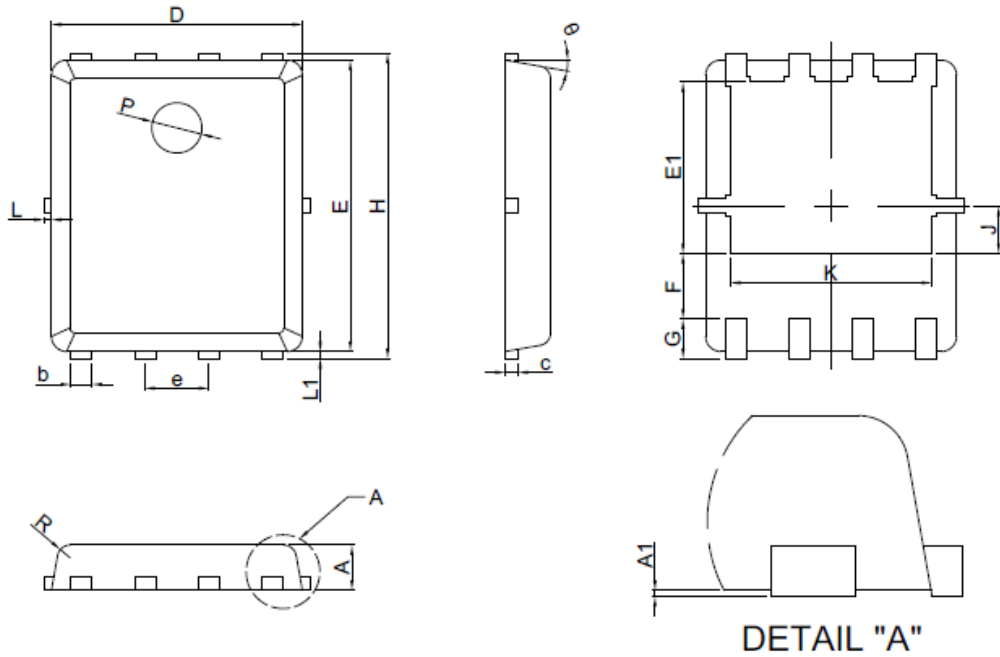
2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Package Information :PDFN5x6-8L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	0.80	1.00
A1	0.00	0.05
b	0.35	0.49
c	0.254REF	
D	4.80	5.20
F	1.40REF	
E	5.60	5.90
e	1.27BSC	
H	5.80	6.20
L1	0.10	0.18
G	0.60REF	
K	4.00REF	
L	-	0.15
J	0.95BSC	
P	1.00REF	
E1	3.40REF	
θ	6°	14°
R	0.25REF	